



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TO-262, TO-263 7L, TO-263 3L</b>					
<b>STRESS</b>	<b>SAMPLE SIZE</b>	<b>DEVICE HOURS/CYCLE</b>	<b>CONDITION</b>	<b>TOTAL FAILS</b>	<b>FAIL PERCENTAGE</b>
Bond int.	280	140 000	200 °C + N2	0	0.00
HAST	1524	165 600	130 °C, 85 % RH	0	0.00
Pressure pot	1430	156 480	121 °C, 15 PSIG	0	0.00
Temp. cycle	1894	1 822 250	-55 °C to -150 °C	0	0.00
Hot test after TC	82	82 000	125 °C, after TC	0	0.00
Solderability	75	600	8 h	0	0.00
Power cycle	983	7 875 564	$\Delta T_J = 100$ °C	0	0.00
Solder dunk	700	45 780	260 °C, 10 s	0	0.00